



Community Member Monthly News – August 2023 – August 30, 2023

[From Different Dimensions](#)

Aug 30, 2023 · By Trine Pierik

News you may not have seen this month from our community members. Along with some upcoming participation to keep an eye on.

Onto Innovation announced over \$100 Million in orders for systems supporting advanced packaging for AI. Its Dragonfly® G3 sub-micron inspection and metrology system supports production of AI chiplet packages. Deliveries are scheduled through the first quarter of 2024, with new orders now extending into the second half of 2024.

In collaboration with McLaren Racing, **Cadence** conducted an interactive masterclass. Madhuparna Datta, application engineer architect, Tal Zigman, group director of Global Academic Partnerships and Ruth Jackson, software architect, shared their career journeys, offering insights to 60 aspiring women in STEM.

On August 24 the Florida Chapter of the [International Microelectronics Assembly and Packaging Society](#) hosted a Workshop & Tabletops on Heterogeneous Integration/System in Package. **Onto Innovation's** Burhan Ali was there presenting "Process Control Solutions for Heterogeneous Integration Through Automated Optical Inspection." Burhan discussed the different technologies that can be embedded in an automated optical inspection system to address a wide range of applications, both 2D and 3D, in advanced packaging technologies.

Micross was at DSEI, in ExCeL London, September 12-15 showcasing its latest Hi-Rel Power and RF Solutions, along with the most comprehensive portfolio of microelectronic products and services. **Amkor Technology, Inc.** marked its 55th year in business and 25th anniversary of being listed on the Nasdaq during the August 28 Nasdaq Closing Bell ceremony. In attendance was Amkor's management, including Founder and Executive Chairman James Kim, and Executive Vice Chairman Susan Kim. **LPKF** participated in Urigas located in Sapporo, Japan in the beautiful Colleagues from LPKF Japan were on hand to show customers how to elevate prototyping to the stage of Rapid Prototyping. **Ajinomoto** became one of the eight lead managing companies of the newly established Health Management Alliance along with 147 other companies and organizations. The Alliance's vision is to "revitalize Japanese companies and achieve sustainability of company-run health insurance societies by promoting employees' well-being." Their two main goals are accelerating value creation by human resources and achieving sustainability of company-run health insurance societies. In IEEE EMC+SIPI 2023, **Xpedic** presented a paper on AI-powered high-speed channel analysis solution. This is a collaborative effort with Cisco in bringing AI to EDA.

Amkor Technology Malaysia (ATM) has launched a new in-house semiconductor plating line. The plating line is essential for enhancing conductivity and reducing wear resistance, as well as for forming conductors and connecting terminals, pads and bumps. This project marks a significant milestone for ATM, enabling us to autonomously support the entire plating process.

EV Group's Justin Yun recently gave a presentation on solutions for wafer-to-wafer and die-to-wafer hybrid bonding at the "Semiconductor Hybrid Bonding Conference" in Seoul, Korea organized by The ELEC, a leading Korean semiconductor and electronics trade publication.

A delegation from the Northern Corridor Implementation Authority (NCIA) in Malaysia, with CEO Mohamad Haris Kader Sultan visited **AT&S** headquarters in Leoben to further intensify professional relations with AT&S. CEO Andreas Gerstenmayer and AT&S are looking forward to further successful cooperation with the NCIA in Malaysia, especially with regard to the creation of a leading IC Substrate & Advanced Packaging Institute, which will benefit both the regional innovation ecosystem and AT&S in the long term as part of the ongoing investment project in Kulim, Malaysia.

Don't Miss!

Dr. Dongshun Bai from **Brewer Science** is a featured speaker at the Advanced Packaging Summit hosted by SEMI in South Korea on September 5th. His presentation, Novel Materials for Advanced Packaging, will answer some of the most pressing questions in the advanced packaging materials industry.

The **QP Technologies** team will travel to New York's Albany Nanotech Complex for this year's Electronics Packaging Symposium, sponsored by Binghamton University, September, 6-7. Topics to be discussed include advanced substrates, power electronics, photonics packaging, and much more.

MKS Atotech representatives will attend the KPCA Show 2023 (booth G201) in Seoul, S. Korea from September 6 – 8. The team will represent MKS's strategic brands, Atotech® and ESI®, and will introduce a new series of solutions for PCB Flex/Rigid-Flex/HDI and package substrate manufacturing.

Cadence announced keynote speakers for the Sept. 12 CadenceLIVE Boston 2023. Thought leaders and visionaries Tom Beckley, Cadence, and Thomas Smelker, Mercury Systems, will discuss the future of electronic system design.

On Sep 12, **Finetech** CTO Sascha Lohse will attend IMAPS-UK EMPC 2023's "Interconnect Material 1" session to present its improved fine pitch micro Indium bump interconnect flip chip bonding process for IR Focal Plane Arrays (FPA).

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